

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD90N03S4L-02	**Issued**	24. February 2022
MA#	MA005700891		
Package	PG-TO252-3-11	**Weight***	372.94 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	1.08	1.08	10802	10802
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		577	
	non noble metal	copper	7440-50-8	215.017	57.65	57.73	576542	577292
wire	non noble metal	aluminium	7429-90-5	5.505	1.48	1.48	14762	14762
encapsulation	inorganic material	zincoxide	1314-13-2	1.218	0.33		3267	
	miscellaneous	miscellaneous	-	6.092	1.63		16336	
	plastics	epoxy resin	-	18.277	4.90		49008	
	inorganic material	silicondioxide	60676-86-0	96.261	25.81	32.67	258111	326722
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10028	10028
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244
solder	non noble metal	tin	7440-31-5	0.065	0.02		173	
	noble metal	silver	7440-22-4	0.081	0.02		217	
	non noble metal	lead	7439-92-1	3.085	0.83	0.87	8272	8662
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.14	5.15	51422	51488
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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